

New RENA WaSep unit separates 3,000 – 6,000 wafers/hour

New version now available

- **Maximum throughput of 6,000 wafers/h**
- **Highest yield by breakage rate < 0.5 %**
- **Wafer adjustment and alignment on a water slide**
- **RENA WaSep operates live at EUPVSEC**

Gütenbach, September 1st, 2011. The latest generation of the RENA WaSep series ensures a reliable and smooth wafer separation with a maximum throughput of 6,000 wafers/h (double unit). With a breakage rate of less than 0.5 % RENA WaSep offers highest yields combined with outstanding throughput. In addition to slurry wafers the system is also suitable for diamond wire sawn wafers.

Function: A wet ribbon directly separates the wafers consistently and stress-free out of a pre-cleaning wafer basket using the special RENA-brush concept. A breakage detection sorter assures that only high quality wafers will be transported to the integrated distribution system. On a water slide, the wafers are adjusted and aligned fully without contacting the wafer in order to avoid any edge defects. This is a unique RENA solution. On the following wet wafer distribution system the wafers are allocated onto four lanes. Throughout the entire process the wafers are kept wet.

The new high throughput version of RENA WaSep operates live at EUPVSEC in Hamburg.

RENA Booth: A1 A1

Contact:
RENA GmbH
Norbert Bürger
Phone: +49 7723 9313-19
Norbert.buerger@rena.com